

# Complementary MOSFET

## ELM4C4903FKA-N

<http://www.elm-tech.com>

### ■General description

ELM4C4903FKA-N uses advanced trench technology to provide excellent  $R_{ds(on)}$ , low gate charge and low gate threshold voltage.

### ■Features

- |  |   |
|--|---|
| N-channel                                    | P-channel                                     |
| • $V_{ds}=40V$                               | • $V_{ds}=-40V$                               |
| • $I_d=23A$ ( $V_{gs}=10V$ )                 | • $I_d=-20A$ ( $V_{gs}=-10V$ )                |
| • $R_{ds(on)} = 28m\Omega$ ( $V_{gs}=10V$ )  | • $R_{ds(on)} = 40m\Omega$ ( $V_{gs}=-10V$ )  |
| • $R_{ds(on)} = 42m\Omega$ ( $V_{gs}=4.5V$ ) | • $R_{ds(on)} = 65m\Omega$ ( $V_{gs}=-4.5V$ ) |

### ■Maximum absolute ratings

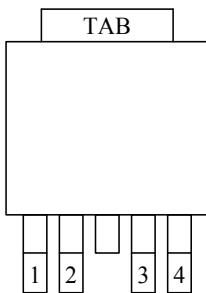
Parameter	Symbol	N-ch (Max.)	P-ch (Max.)	Unit	Note
Drain-source voltage	$V_{ds}$	40	-40	V	
Gate-source voltage	$V_{gs}$	$\pm 20$	$\pm 20$	V	
Continuous drain current ( $V_{gs}=10V$ )	$I_d$	23	-20	A	1
$T_c=100^{\circ}C$		18	-16		
Pulsed drain current	$I_{dm}$	46	-40	A	2
Single pulse avalanche energy	$E_{AS}$	28	66	mJ	3
Avalanche current	$I_{as}$	17.8	-27.2	A	
Power dissipation	$P_d$	25.0	31.3	W	4
Storage temperature range	$T_{stg}$	-55 to 150	-55 to 150	$^{\circ}C$	
Operating junction temperature range	$T_j$	-55 to 150	-55 to 150	$^{\circ}C$	

### ■Thermal Characteristics

Parameter	Symbol	Typ.	Max.	Unit	Note
Thermal resistance junction-to-ambient	$R_{\theta ja}$	-	62	$^{\circ}C/W$	1
Thermal resistance junction-case	$R_{\theta jc}$	-	5	$^{\circ}C/W$	1

### ■Pin configuration

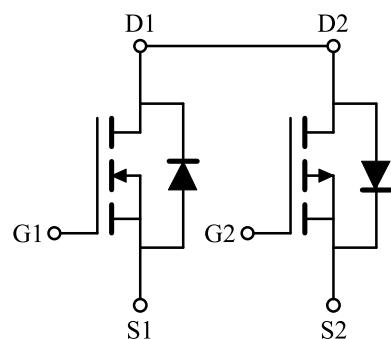
TO-252-4(TOP VIEW)



Pin No.	Pin name
1	SOURCE1
2	GATE1
3	SOURCE2
4	GATE2
TAB	DRAIN1/DRAIN2

### ■Circuit

- N-ch
- P-ch



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### ■Electrical characteristics (N-ch)

T<sub>j</sub>=25°C. Unless otherwise noted.

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit	Note
<b>STATIC PARAMETERS</b>							
Drain-source breakdown voltage	BVdss	V <sub>gs</sub> =0V, I <sub>d</sub> =250μA	40	-	-	V	
Static drain-source on-resistance	R <sub>ds(on)</sub>	V <sub>gs</sub> =10V, I <sub>d</sub> =12A	-	-	28	mΩ	2
		V <sub>gs</sub> =4.5V, I <sub>d</sub> =10A	-	-	42		
Gate threshold voltage	V <sub>gs(th)</sub>	V <sub>gs</sub> =V <sub>ds</sub> , I <sub>d</sub> =250μA	1.0	1.5	2.5	V	
Zero gate voltage drain current	I <sub>dss</sub>	V <sub>ds</sub> =32V, V <sub>gs</sub> =0V	-	-	1	μA	
		V <sub>ds</sub> =32V, V <sub>gs</sub> =0V, T <sub>j</sub> =55°C	-	-	5		
Gate-body leakage current	I <sub>gss</sub>	V <sub>gs</sub> =±20V, V <sub>ds</sub> =0V	-	-	±100	nA	
Forward transconductance	G <sub>f</sub> s	V <sub>ds</sub> =5V, I <sub>d</sub> =12A	-	8	-	S	
Max. body-diode continuous current	I <sub>s</sub>	V <sub>gs</sub> =V <sub>ds</sub> =0V, Force current	-	-	23	A	1, 5
Pulsed source current	I <sub>sm</sub>		-	-	46	A	2, 5
Diode forward voltage	V <sub>sd</sub>	V <sub>gs</sub> =0V, I <sub>s</sub> =1A	-	-	1.2	V	2
<b>DYNAMIC PARAMETERS</b>							
Input capacitance	C <sub>iss</sub>	V <sub>ds</sub> =15V, V <sub>gs</sub> =0V, f=1MHz	-	593	-	pF	
Output capacitance	C <sub>oss</sub>		-	76	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>		-	56	-	pF	
Gate resistance	R <sub>g</sub>	V <sub>ds</sub> =0V, V <sub>gs</sub> =0V, f=1MHz	-	2.6	5.2	Ω	
<b>SWITCHING PARAMETERS</b>							
Total gate charge (4.5V)	Q <sub>g</sub>	V <sub>ds</sub> =20V, V <sub>gs</sub> =4.5V I <sub>d</sub> =12A	-	5.50	-	nC	
Gate-source charge	Q <sub>gs</sub>		-	1.25	-	nC	
Gate-drain charge	Q <sub>gd</sub>		-	2.50	-	nC	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>ds</sub> =20V, V <sub>gs</sub> =10V R <sub>gen</sub> =3.3Ω, I <sub>d</sub> =1A	-	8.9	-	ns	
Turn-on rise time	t <sub>r</sub>		-	2.2	-	ns	
Turn-off delay time	t <sub>d(off)</sub>		-	41.0	-	ns	
Turn-off fall time	t <sub>f</sub>		-	2.7	-	ns	

#### NOTE :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width ≤ 300μs and duty cycle ≤ 2%.
3. The EAS data shows Max. rating . The test condition is V<sub>dd</sub>=25V, V<sub>gs</sub>=10V, L=0.1mH, I<sub>as</sub>=17.8A.
4. The power dissipation is limited by 150°C junction temperature.
5. The data is theoretically the same as I<sub>d</sub> and I<sub>dm</sub>, in real applications, should be limited by total power dissipation.

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## ■Typical electrical and thermal characteristics (N-ch)

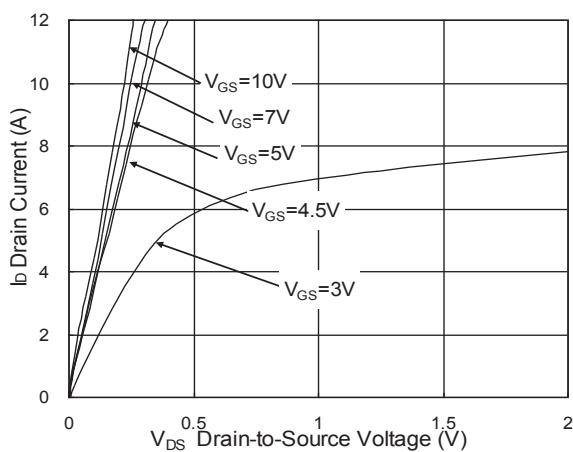


Fig.1 Typical Output Characteristics

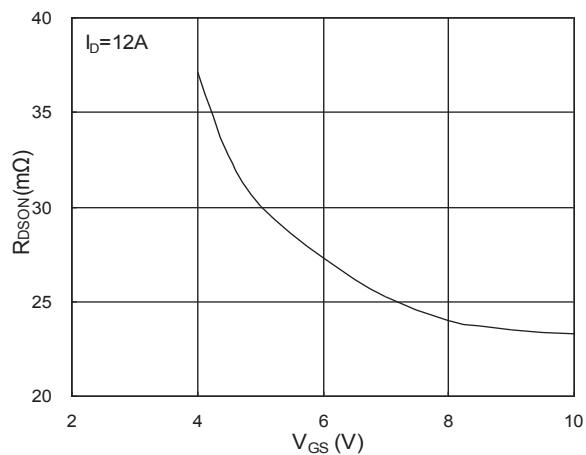


Fig.2 On-Resistance vs. G-S Voltage

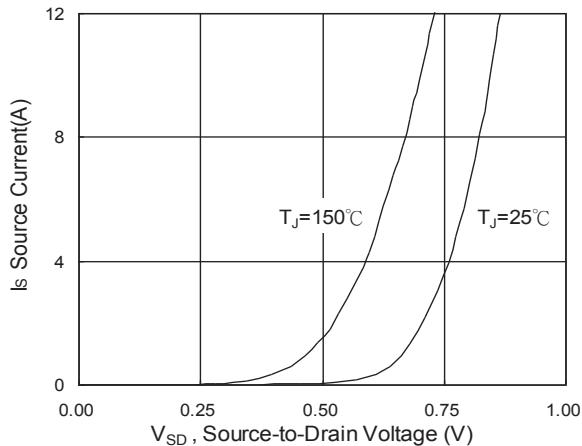


Fig.3 Forward Characteristics of Reverse

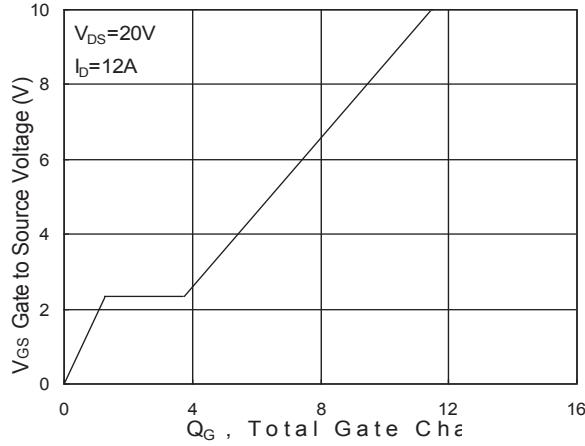


Fig.4 Gate-Charge Characteristics

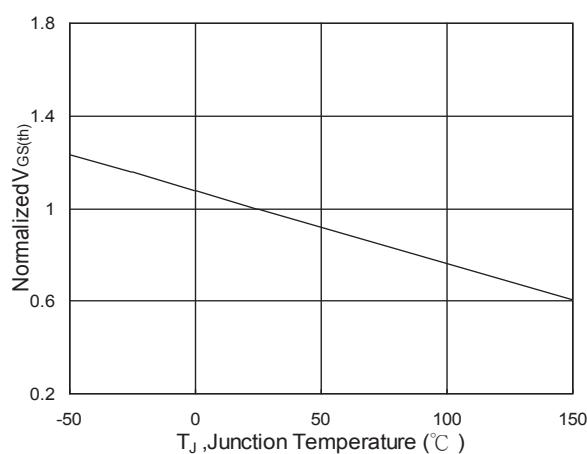


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

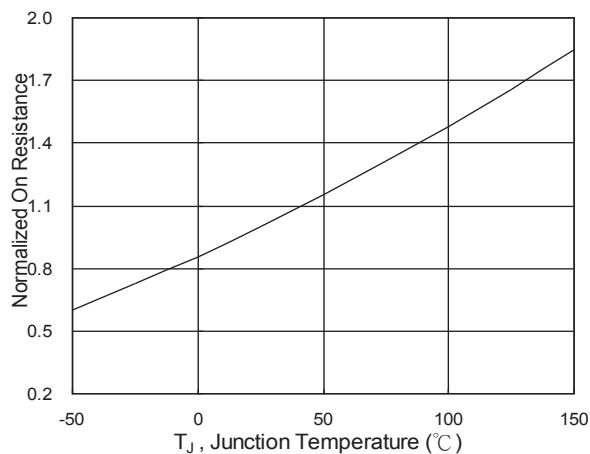


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

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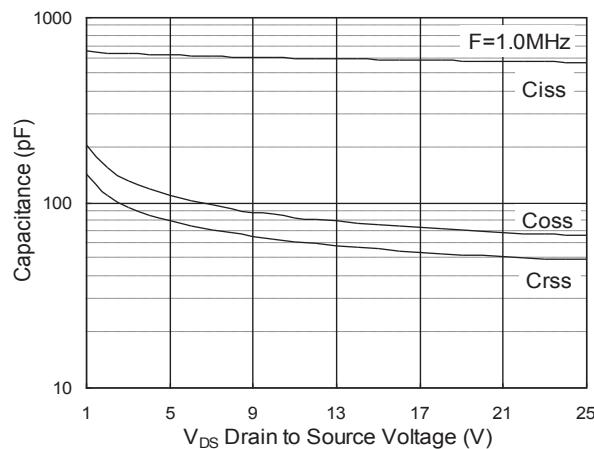


Fig.7 Capacitance

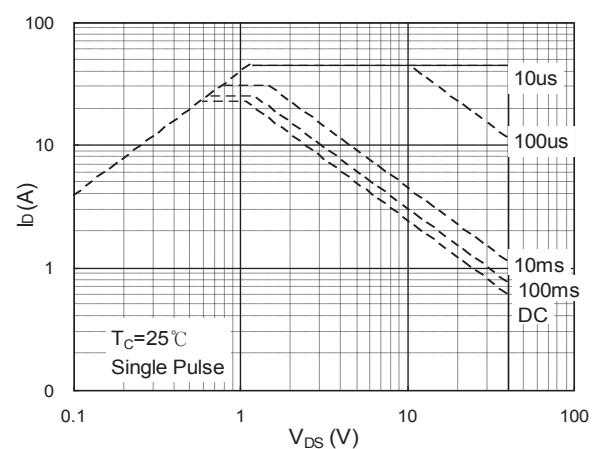


Fig.8 Safe Operating Area

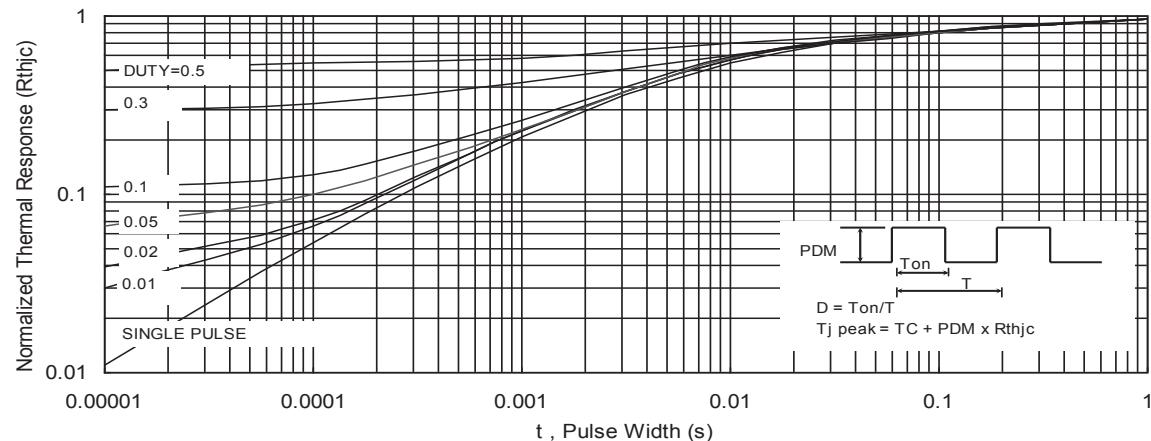


Fig.9 Normalized Maximum Transient Thermal Impedance

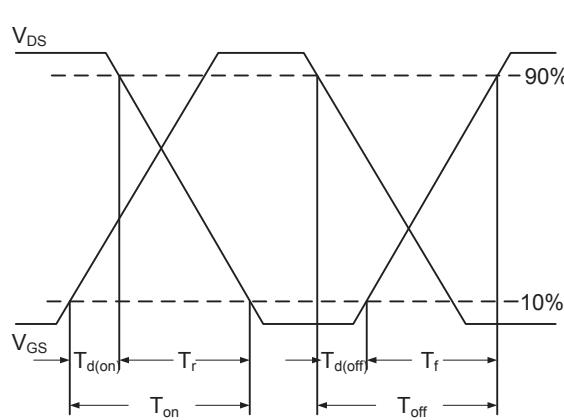


Fig.10 Switching Time Waveform

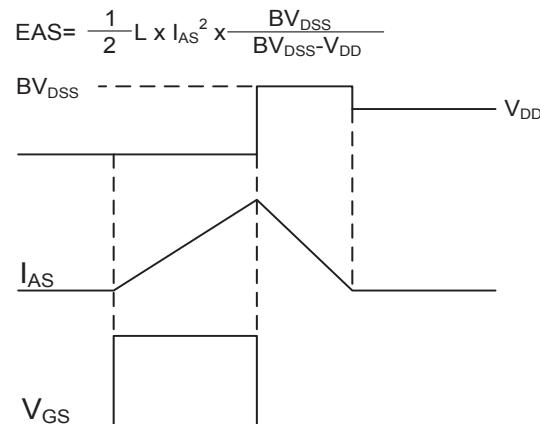


Fig.11 Unclamped Inductive Switching Wave

# Complementary MOSFET

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### ■Electrical Characteristics (P-ch)

$T_j=25^\circ\text{C}$ . Unless otherwise noted.

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit	Note
<b>STATIC PARAMETERS</b>							
Drain-source breakdown voltage	BVdss	V <sub>gs</sub> =0V, I <sub>d</sub> =-250μA	-40	-	-	V	
Static drain-source on-resistance	R <sub>ds(on)</sub>	V <sub>gs</sub> =-10V, I <sub>d</sub> =-8A	-	-	40	mΩ	2
		V <sub>gs</sub> =-4.5V, I <sub>d</sub> =-4A	-	-	65		
Gate threshold voltage	V <sub>gs(th)</sub>	V <sub>gs</sub> =V <sub>ds</sub> , I <sub>d</sub> =-250μA	-1.0	-1.6	-2.5	V	
Zero gate voltage drain current	I <sub>dss</sub>	V <sub>ds</sub> =-32V, V <sub>gs</sub> =0V	-	-	-1	μA	
		V <sub>ds</sub> =-32V, V <sub>gs</sub> =0V, T <sub>j</sub> =55°C	-	-	-5		
Gate-body leakage current	I <sub>gss</sub>	V <sub>gs</sub> =±20V, V <sub>ds</sub> =0V	-	-	±100	nA	
Forward transconductance	G <sub>f</sub> s	V <sub>ds</sub> =-5V, I <sub>d</sub> =-8A	-	12.6	-	S	
Max. body-diode continuous current	I <sub>s</sub>	V <sub>gs</sub> =V <sub>ds</sub> =0V, Force current	-	-	-20	A	1, 5
Pulsed source current	I <sub>sm</sub>		-	-	-40	A	2, 5
Diode forward voltage	V <sub>sd</sub>	V <sub>gs</sub> =0V, I <sub>s</sub> =-1A	-	-	-1	V	2
<b>DYNAMIC PARAMETERS</b>							
Input capacitance	C <sub>iss</sub>	V <sub>ds</sub> =-15V, V <sub>gs</sub> =0V, f=1MHz	-	1004	-	pF	
Output capacitance	C <sub>oss</sub>		-	108	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>		-	80	-	pF	
Gate resistance	R <sub>g</sub>	V <sub>ds</sub> =0V, V <sub>gs</sub> =0V, f=1MHz	-	13	16	Ω	
<b>SWITCHING PARAMETERS</b>							
Total gate charge (-4.5V)	Q <sub>g</sub>	V <sub>ds</sub> =-20V, V <sub>gs</sub> =-4.5V I <sub>d</sub> =-12A	-	9.00	-	nC	
Gate-source charge	Q <sub>gs</sub>		-	2.54	-	nC	
Gate-drain charge	Q <sub>gd</sub>		-	3.10	-	nC	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>ds</sub> =-15V, V <sub>gs</sub> =-10V R <sub>gen</sub> =3.3Ω, I <sub>d</sub> =-1A	-	19.2	-	ns	
Turn-on rise time	t <sub>r</sub>		-	12.8	-	ns	
Turn-off delay time	t <sub>d(off)</sub>		-	48.6	-	ns	
Turn-off fall time	t <sub>f</sub>		-	4.6	-	ns	

#### NOTE :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width  $\leq 300\mu\text{s}$  and duty cycle  $\leq 2\%$ .
3. The EAS data shows Max. rating . The test condition is V<sub>dd</sub>=-25V, V<sub>gs</sub>=-10V, L=0.1mH, I<sub>as</sub>=-27.2A.
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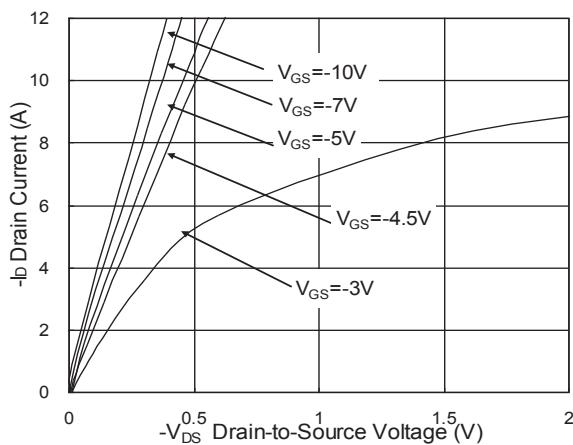


Fig.1 Typical Output Characteristics

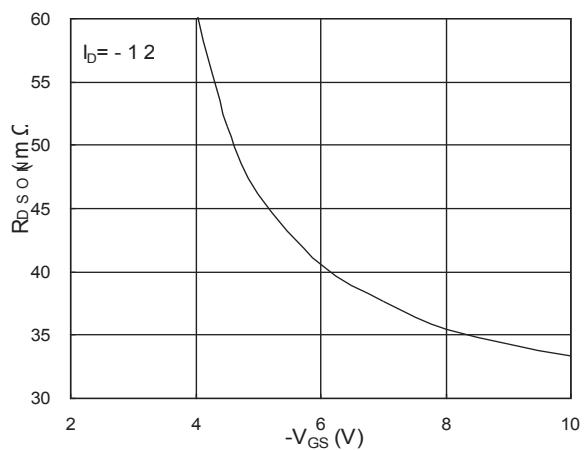


Fig.2 On-Resistance v.s Gate-Source

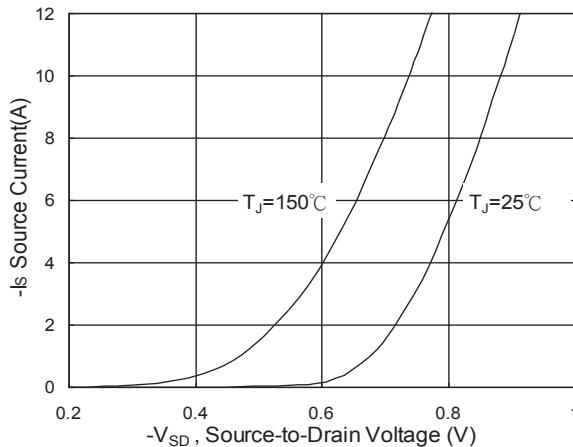


Fig.3 Forward Characteristics of Reverse

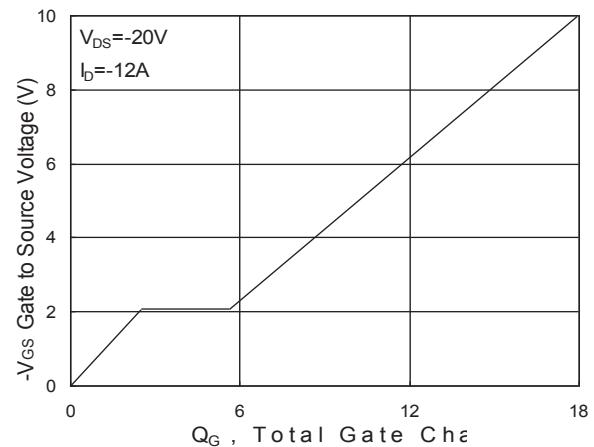


Fig.4 Gate-Charge Characteristics

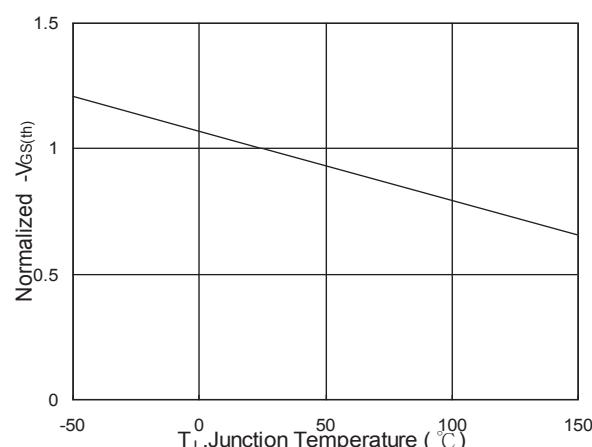


Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$

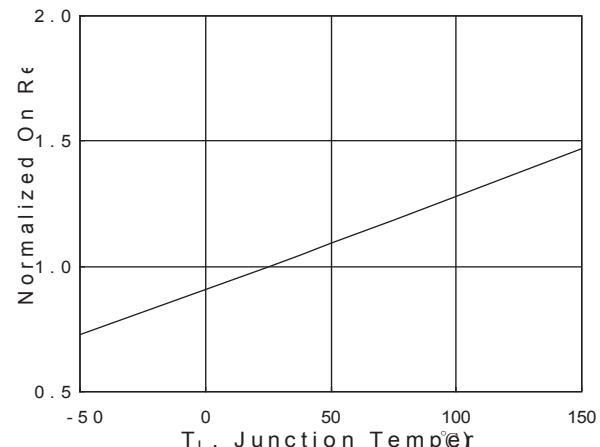


Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$

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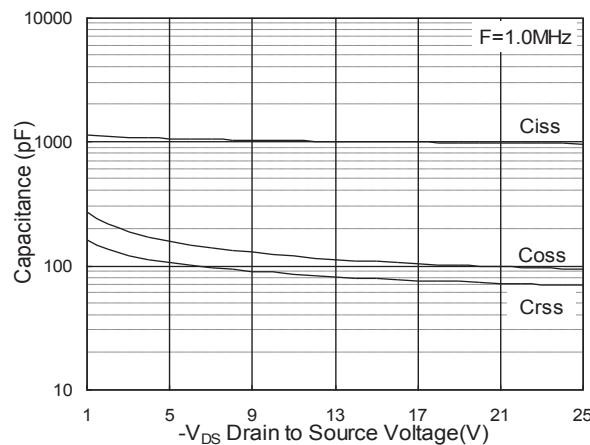


Fig.7 Capacitance

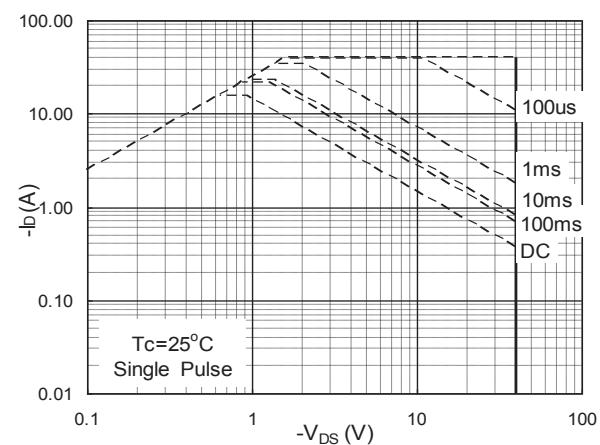


Fig.8 Safe Operating Area

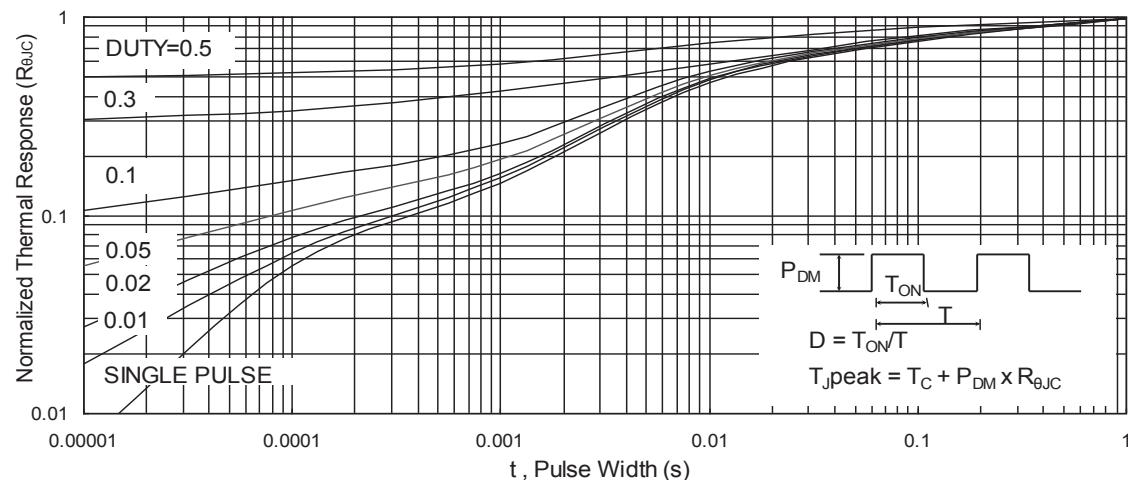


Fig.9 Normalized Maximum Transient Thermal Impedance

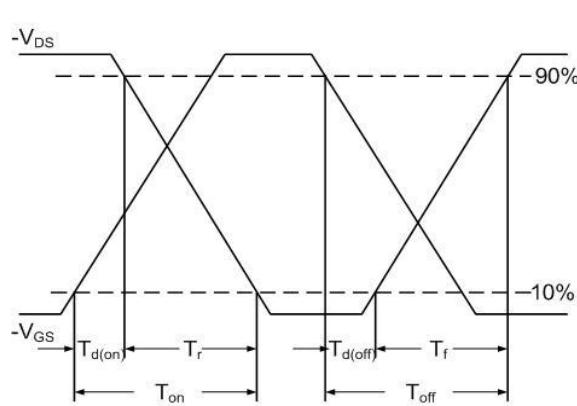


Fig.10 Switching Time Waveform

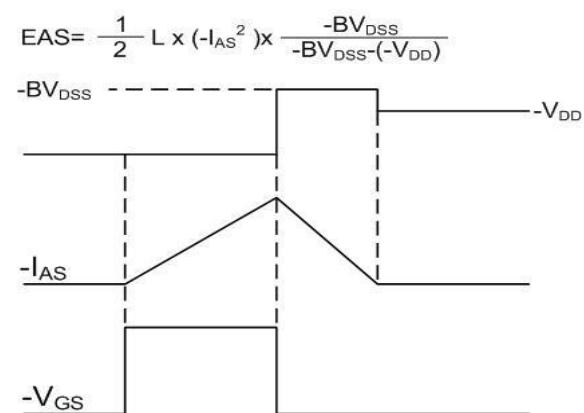


Fig.11 Unclamped Inductive Waveform